



Advanced Electronic Packaging Technology: From Hard to Soft

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Message from the Guest Editors

This Special Issue will address advances in Electronic Packaging Technology, including design, structure, material, processing, and testing of electronic and photonic devices. Electronic devices have been rapidly developing with the growing necessities of high-computing, low-power consumption, miniaturization, and multi-function in computers and consumer electronics products.

Soft electronic packaging represents one of the most promising approaches to form imperceptive and comfortable interfaces of human and electronic devices. In this regard, the demonstration of advanced soft materials, structures, and design in advanced electronic packaging is strongly demanded to comply with the requirements of the developments of soft electronic devices.

Original papers are solicited on all types of advanced electronic packaging technologies involving designs, structures, materials, processing, and testing. For more information, please click into the website at: https://www.mdpi.com/journal/materials/special_issues/electronic_packaging (or: [mdpi.com/si/103244](https://www.mdpi.com/si/103244))





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Message from the Editor-in-Chief

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